

參考文獻

- [1] 楊文螢、莊凱婷、劉永光，“LCD 生產設備專題研究”
(ITRIMI-0267-S108(87)，工研院(財團法人工業技術研究院)，
1988.
- [2] 崔世和，“捲帶式晶粒接合技術”，工研院機械所，pp. 1-12，民
國 78 年 5 月。
- [3] K. Hatada, “Trend of New Package Development... TAB
Technology, Technical Proceedings Semicon”, Japan, 1988.
- [4] 畑田，“TAB 実装技術の最新動向と今後の展開”，電子材料，
p. 25，1989 年 5 月号。
- [5] T. Kokohawa, H. Otsuki, K. Niki, K. Adachi, and H. Takasago,
“Fine Pitch Lead Bonding Technology for
LCDs”Int. Microelec. Conf. Proc., pp. 196-201, 1990.
- [6] 潘金平，“TAB 構裝最新發展趨勢”，工業材料 127 期，pp. 97-104，
民國 86 年 7 月。
- [7] 胡應強、邱以泰，“TAB 技術應用與可靠度”，工業材料 165 期，
pp. 137-140，民國 89 年 9 月。
- [8] 李宗銘，“異方性導電膠材料技術與應用”，工業材料 147 期，pp.
93-98，民國 88 年 3 月..
- [9] R. Dudek, A. Schubert, S. Meinel, and B. Michael, “Flow
Characterization and Thermo-mechanical Response of
Anisotropic Conductive Films”, IEEE Proceedings of 3rd
international Conference, pp. 68-75, 1998.
- [10] N. R. Basavanhally, David D. Chang, and Benjamin H. Cranston,
“Direct Chip Interconnect with Adhesive-Connector
Films”, Proceeding of Electronic Components and
Technology Conference, pp. 491-498, 1992.
- [11] N. H. Yeung, C. M. L. Wu, and J. K. L. Lai, “Thermal Cycling

- Analysis of TAB OLB Connection With ACF”, IEEE Proceedings of 3rd international Conference, pp. 206–210, 1998.
- [12] M. Yamaguchi, F. Asai, F. Eriguchi, Y. Hotta, “Development of Novel Anisotropic Conductive Film(ACF)”, IEEE Electronic Components and Technology Conference, pp. 360–364, 1999.
- [13] M. J. Yim, K. W. Paik, “Design and Understanding of Anisotropic Conductive Films(ACF’s)for LCD Packaging”, IEEE Transaction on Components, Packaging and Manufacturing Technology----Part A, Vol. 21, No. 2, June 1998.
- [14] R. Ascenbrenner, A. Ostmann, G. Mountlla, E. Zake1, and H. Reichl, “Flip Chip Attachment Using Anisotropic Conductive Adhesives and Electroless Nickel Bumps”, IEEE Transaction on Components, Packaging and Manufacturing Technology----Part C, Vol. 20, No. 2, pp. 95–100, April 1997.
- [15] M. J. Yim, K. W. Paik, T. S. Kim, and Y. K. Kim, “Anisotropic Conductive Film(ACF) Interconnection for Display Packaging Applications”, IEEE Electronic Components and Technology Conference, pp. 1036–1041, 1998.
- [16] H. Kristiansen, and J. Liu, Overview of Conductive Adhesive Interconnection Technology for LCDs “, IEEE International Symposium, pp. 223–232, 1997.
- [17] K. Hatada, A New LSI bonding technology “Micron Bump Bonding Assembly Technology” , IEEE International Electronic Manufacturing Technology Symposium Proceeding, pp. 23–27, Oct. 10–12 1988.
- [18] K. Hatada, “Bump property for high bondability and reliability in Transferred Bump TAB Technology” , IMC

- Proceeding, pp. 440, 1988.
- [19] D. Carmen, Burns, “Trends in Tape Bonding” , Semiconductor International, pp. 25–30, April 1979.
- [20] M. Inaba, “Solder Bump Formation Using Electroless Plating and Ultrasonic Soldering” , IEEE-CHMT Proceedings, p. 13, Oct. 1988.
- [21] J. – Y. Tseng, Daivd R. J. Lin, W. – H. Hsu, and M. C. Chi, “A Router for Tape Automated Bonding Packages” , 5th International Symposium on IC Technology, System & Applications 1993.
- [22] J. – Y. Tseng, Daivd R. J. Lin, and M. C. Chi, “A Floorplanning System for Tape Automated Bonding Packages” , 6th IEEE ASIC Conference 1993.
- [23] I. Jung, T. Lee, J. Break, and H. Kim, “Optimization of TAB Inner Lead Bonding Process” , Annual IEEE Semiconductor Thermal Measurement and Management Symposium, pp. 129–135, 1996.
- [24] J. H. Lau, D. W. Rice, and C. G. Harkins, “Thermal Stress Analysis of Tape Automated Bonding Packages and Interconnections” , IEEE Transaction on Components, Hybrids, and Manufacturing Technology, Vol. 13, No1, pp. 182–187, 1990.
- [25] E. Zake1, and H. Reichl “Au-Sn Bonding Metallurgy of TAB Contacts and Its Influence on the Kirkendall Effect in the Ternary Cu–Au–Sn” , IEEE Transaction on Components, Hybrids, and Manufacturing Technology, Vol16, 13, No3, pp. 323–332, 1993.

- [26] 謝芳宜，“液晶顯示器構裝技術”，工業材料 147 期，
pp. 107-113，1999.
- [27] 胡足庚，“TAB 之捲帶設計與製作”，電子發展月刊，
Vol. 148, pp. 56-66, 1990.
- [28] 陸蘇龍、徐道明、石鏗鏘、李俊明，“COG 構裝設備技術簡介”，
機械工業雜誌 219 期，pp. 129-133，June 1990.
- [29] 林榮堅、曾中英、陳美麗，“用於捲帶式晶粒接合(TAB)封裝的
佈局規畫系統”，電腦與通訊 26 期，pp. 24-28，1994.
- [30] 畠田賢造原著，卓聖鵬編譯，“TAB 技術入門”，全華科技圖書，
pp. 24-28，pp. 64-70，pp. 187-220，民國 82 年 6 月.

